



PRELIMINARY

SOLID STATE DEVICES, INC

14849 Firestone Boulevard · La Mirada, CA 90638
Phone: (714) 670-SSDI (7734) · Fax: (714) 522-7424

Designer's Data Sheet

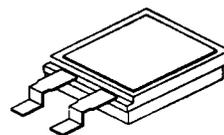
FEATURES:

- Rugged construction with poly silicon gate
- Low RDS(on) and high transconductance
- Excellent high temperature stability
- Very fast switching speed
- Fast recovery and superior dv/dt performance
- Increased reverse energy capability
- Low input and transfer capacitance for easy paralleling
- Hermetically sealed surface mount package
- Low inductance package
- TX, TXV and Space Level screening available
- Replaces: IRF230 Types

SFF230G

**9 AMP
200 VOLTS
0.40Ω
N-CHANNEL
POWER MOSFET**

CERPACK



MAXIMUM RATINGS

| CHARACTERISTIC | SYMBOL | VALUE | UNIT |
|--------------------------------------|------------------------------------|-------------|-------|
| Drain to Source Voltage | V _{DS} | 200 | Volts |
| Gate to Source Voltage | V _{GS} | ±20 | Volts |
| Continuous Drain Current | I _D | 9 | Amps |
| Operating and Storage Temperature | T _{op} & T _{stg} | -55 to +150 | °C |
| Thermal Resistance, Junction to Case | R _{θJC} | 2.8 | °C/W |
| Total Device Dissipation @ TC=25°C | P _D | 45 | Watts |
| Total Device Dissipation @ TC=55°C | | 34 | |

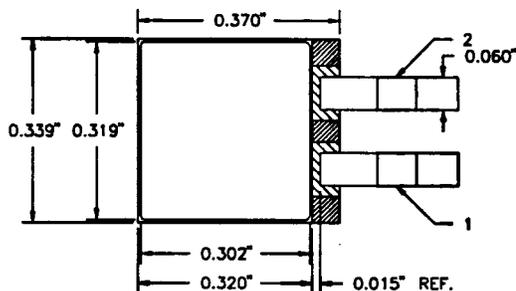
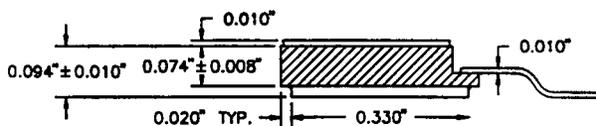
PACKAGE OUTLINE: CERPACK

PIN OUT:

PIN 1: SOURCE

PIN 2: GATE

CASE: DRAIN



NOTE: All specifications are subject to change without notification. SCD's for these devices should be reviewed by SSDI prior to release.

DATA SHEET #: F0007 B

MED

SFF230G

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Phone: (714) 670-SSDI (7734) · Fax: (714) 522-7424**ELECTRICAL CHARACTERISTICS @ T_J=25°C (Unless Otherwise Specified)**

| RATING | SYMBOL | MIN | TYP | MAX | UNIT |
|---|--|-----|------------------|----------------------|------------|
| Drain to Source Breakdown Voltage (V _{GS} =0 V, I _D =250μA) | BV _{DSS} | 200 | --- | --- | V |
| Drain to Source on State Resistance (V _{GS} =10 V, I _D = 5 A) | R _{DS(on)} | --- | 0.25 | 0.4 | Ω |
| On State Drain Current (V _{DS} > I _{D(on)} X R _{DS(on)} Max, V _{GS} =10 V) | I _{D(on)} | 9 | --- | --- | A |
| Gate Threshold Voltage (V _{DS} =V _{GS} , I _D =250μA) | V _{GS(th)} | 2 | --- | 4 | V |
| Forward Transconductance (V _{DS} > I _{D(on)} X R _{DS(on)} Max, I _{DS} = 5 A) | g _{fs} | 3.0 | 6 | --- | S(Ω) |
| Zero Gate Voltage Drain Current (V _{DS} =max rated voltage, V _{GS} =0 V) (V _{DS} =80% rated V _{DS} , V _{GS} =0 V, T _A =125°C) | I _{DSS} | --- | --- | 250 1000 | μA |
| Gate to Source Leakage Forward Gate to Source Leakage Reverse | At rated V _{GS} I _{GSS} | --- | --- | 100 -100 | nA |
| Total Gate Charge Gate to Source Charge Gate to Drain Charge | V _{GS} =10 Volts 80% rated V _{DS} I _D = 12 A Q _g Q _{gs} Q _{gd} | --- | 30 10 9 | 39 --- | nC |
| Turn on Delay Time Rise Time Turn Off Delay Time Fall Time | V _{DD} =50% rated V _{DS} 50% rated I _D R _G = 15Ω t _{d(on)} t _r t _{d(off)} t _f | --- | --- | 30 50 50 40 | nsec |
| Diode Forward Voltage (I _S =rated I _D , V _{GS} =0 V, T _J =25°C) | V _{SD} | --- | --- | 2.0 | V |
| Diode Reverse Recovery Time Reverse Recovery Charge | T _J =150°C I _F =rated I _D di/dt=100 A/μsec t _{rr} Q _{RR} | --- | 450 3.0 | --- | nsec μC |
| Input Capacitance Output Capacitance Reverse Transfer Capacitance | V _{GS} =0 Volts V _{DS} =25 Volts f= 1 MHz C _{iss} C _{oss} C _{rss} | --- | 600 250 80 | 800 450 150 | pF |

SAFE OPERATING AREA (S.O.A.)
T_C = 25°C, D.C. CONDITION